

Abstract Submitted
for the SES06 Meeting of
The American Physical Society

Shear Strength and Microstructure of Sn-3Ag-0.5Cu Solder Joints¹ SYLVESTER EKPENUMA, Clafin University, MIN HE, VIOLA ACOFF, The University of Alabama — Sn-Ag-Cu based solders have been studied extensively as they show great promise for use in electronics assembly and packaging industry as alternatives to Sn-Pb based solders. As a further test of the reliability of these solders, the shear strength of single lap shear Sn-Ag-Cu solder joints was investigated. The microstructures of the solder joints and the fracture surfaces were examined using SEM.

¹Work supported by NSF grant DMR-0349851

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Date submitted: 22 Aug 2006

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